

General purpose JFET quad operational amplifier

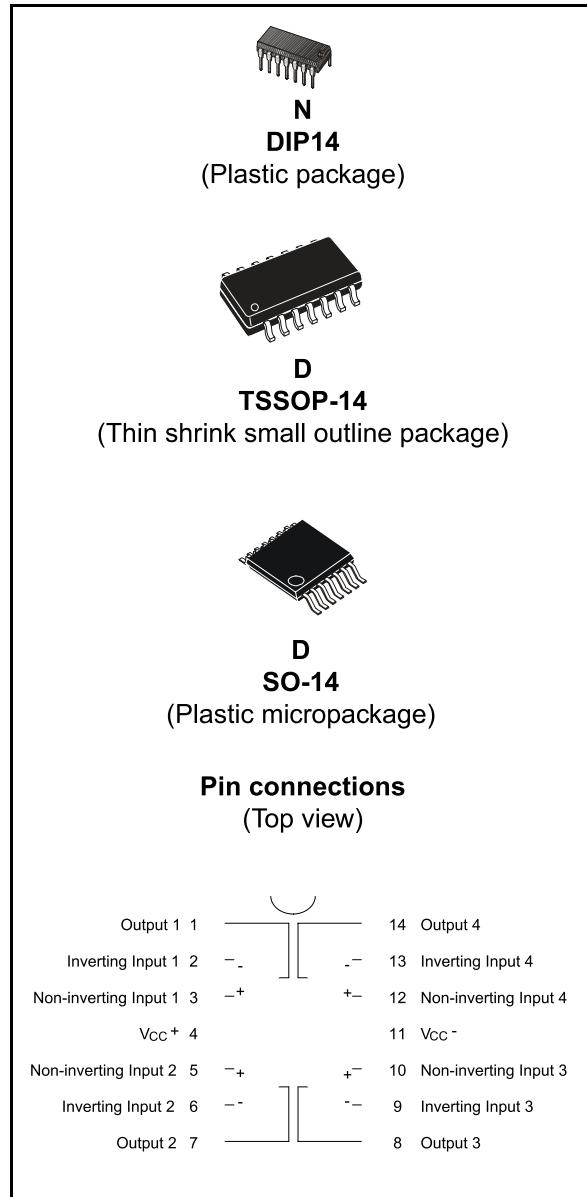
Features

- Wide common-mode (up to V_{CC}^+) and differential voltage range
- Low input bias and offset current
- Output short-circuit protection
- High input impedance JFET input stage
- Internal frequency compensation
- Latch up free operation
- High slew rate: 16V/ μ s (typ)

Description

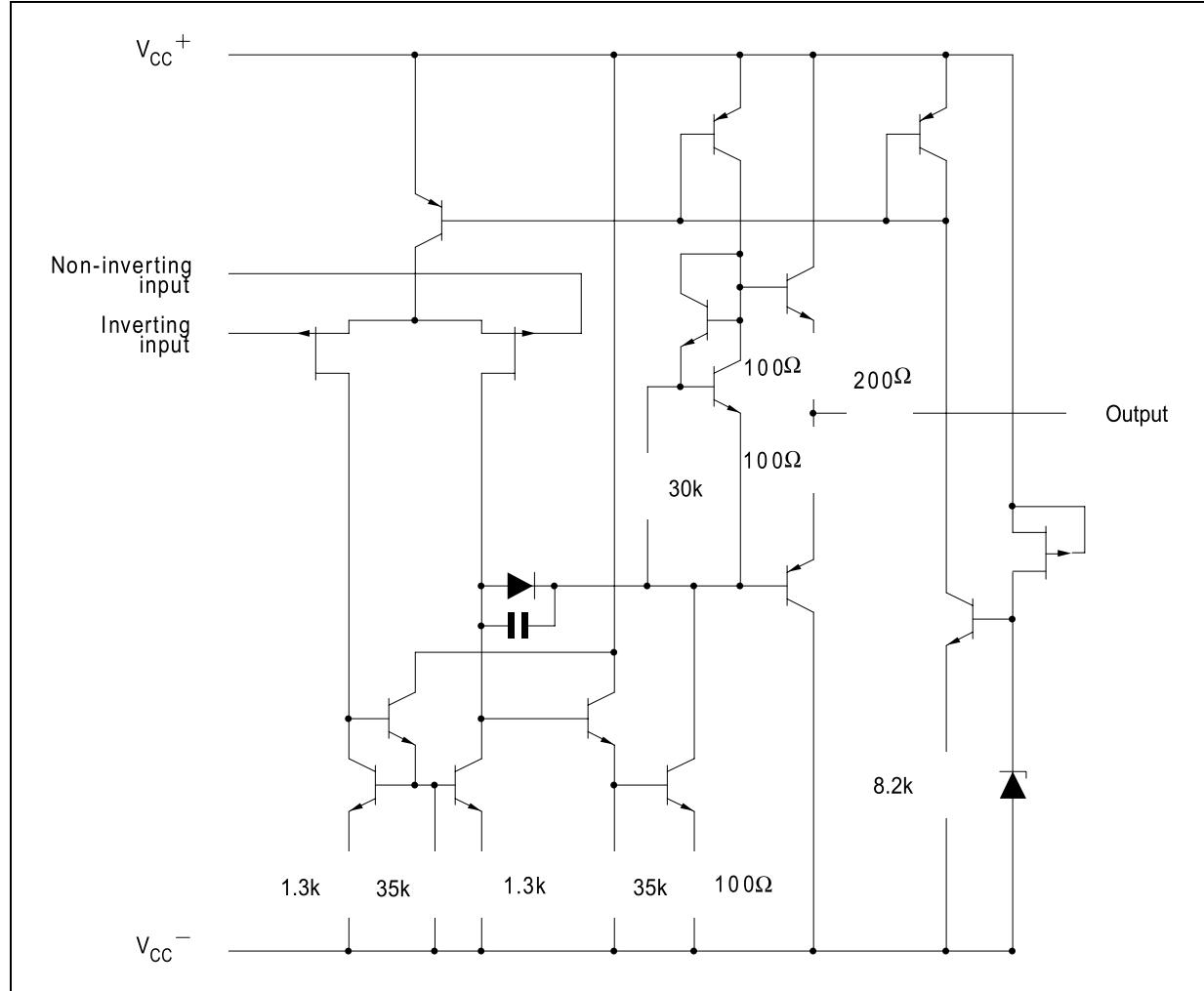
The TL084, TL084A and TL084B are high-speed JFET input quad operational amplifiers incorporating well matched, high voltage JFET and bipolar transistors in a monolithic integrated circuit.

The devices feature high slew rates, low input bias and offset currents, and low offset voltage temperature coefficient.



1 Schematic diagram

Figure 1. Circuit schematics (for each amplifier)



2 Absolute maximum ratings and operating conditions

Table 1. Absolute maximum ratings

Symbol	Parameter	Value			Unit	
		TL084M, AM, BM	TL084I, AI, BI	TL084C, AC, BC		
V_{CC}	Supply voltage (1)	± 18			V	
V_i	Input voltage (2)	± 15			V	
V_{id}	Differential input voltage (3)	± 30			V	
R_{thja}	Thermal resistance junction to ambient ^{(4) (5)} SO-14 DIP14 TSSOP14	105 80 100			°C/W	
R_{thjc}	Thermal resistance junction to case ^{(4) (5)} SO-14 DIP14 TSSOP14	31 33 32			°C/W	
P_{tot}	Power dissipation	680			mW	
	Output short-circuit duration (6)	Infinite				
T_{oper}	Operating free-air temperature range	-55 to +125	-40 to +105	0 to +70	°C	
T_{stg}	Storage temperature range	-65 to +150			°C	
ESD	HBM: human body model ⁽⁷⁾	1000			V	
	MM: machine model ⁽⁸⁾	150				
	CDM: charged device model ⁽⁹⁾	1500				

- All voltage values, except differential voltage, are with respect to the zero reference level (ground) of the supply voltages where the zero reference level is the midpoint between V_{CC}^+ and V_{CC}^- .
- The magnitude of the input voltage must never exceed the magnitude of the supply voltage or 15 volts, whichever is less.
- Differential voltages are the non-inverting input terminal with respect to the inverting input terminal.
- Short-circuits can cause excessive heating and destructive dissipation.
- R_{th} are typical values.
- The output may be shorted to ground or to either supply. Temperature and/or supply voltages must be limited to ensure that the dissipation rating is not exceeded.
- Human body model: 100pF discharged through a 1.5kΩ resistor between two pins of the device, done for all couples of pin combinations with other pins floating.
- Machine model: a 200pF cap is charged to the specified voltage, then discharged directly between two pins of the device with no external series resistor (internal resistor < 5Ω), done for all couples of pin combinations with other pins floating.
- Charged device model: all pins plus package are charged together to the specified voltage and then discharged directly to the ground.

Table 2. Operating conditions

Symbol	Parameter	TL084M, AM, BM	TL084I, AI, BI	TL084C, AC, BC	Unit
V_{CC}	Supply voltage range	6 to 36			V
T_{oper}	Operating free-air temperature range	-55 to +125	-40 to +105	0 to +70	°C

3 Electrical characteristics

Table 3. $V_{CC} = \pm 15V$, $T_{amb} = +25^{\circ}C$ (unless otherwise specified)

Symbol	Parameter	TL084I,M,AC,AI,AM, BC,BI,BM			TL084C			Unit
		Min.	Typ.	Max.	Min.	Typ.	Max.	
V_{io}	Input offset voltage ($R_s = 50\Omega$)							mV
	$T_{amb} = +25^{\circ}C$ TL084		3	10			3	
	TL084A		3	6				
	TL084B		1	3				
	$T_{min} \leq T_{amb} \leq T_{max}$ TL084			13			13	
DV_{io}	TL084A			7				$\mu V/^{\circ}C$
	TL084B			5				
						10		
I_{io}	Input offset current							pA nA
	$T_{amb} = +25^{\circ}C$		5	100			5	
I_{ib}	$T_{min} \leq T_{amb} \leq T_{max}$		4				4	pA nA
	Input bias current ⁽¹⁾						30	
	$T_{amb} = +25^{\circ}C$		20	200			200	
A_{vd}	$T_{min} \leq T_{amb} \leq T_{max}$		20	200			20	V/mV
	Large signal voltage gain ($R_L = 2k\Omega$, $V_o = \pm 10V$)	50	200		25	200		
	$T_{amb} = +25^{\circ}C$	25			15			
SVR	$T_{min} \leq T_{amb} \leq T_{max}$	80	86		70	86		dB
	Supply voltage rejection ratio ($R_S = 50\Omega$)	80	80		70	70		
I_{cc}	$T_{amb} = +25^{\circ}C$		1.4	2.5			1.4	mA
	$T_{min} \leq T_{amb} \leq T_{max}$			2.5			2.5	
	Supply current, no load						2.5	
V_{icm}	$T_{amb} = +25^{\circ}C$							V
	$T_{min} \leq T_{amb} \leq T_{max}$							
	Input common mode voltage range	± 11	+15 -12		± 11	+15 -12		
CMR	Common mode rejection ratio ($R_S = 50\Omega$)	80	86		70	86		dB
	$T_{amb} = +25^{\circ}C$	80			70			
I_{os}	$T_{min} \leq T_{amb} \leq T_{max}$	10	40	60	10	40	60	mA
	Output short-circuit current	10		60	10		60	
$\pm V_{opp}$	$T_{amb} = +25^{\circ}C$	10	12		10	12		V
	$RL = 2k\Omega$				12			
	$RL = 10k\Omega$	12	13.5			12	13.5	
	$T_{min} \leq T_{amb} \leq T_{max}$	10			10			
	$RL = 2k\Omega$	10			12			
SR	$RL = 10k\Omega$	12						$V/\mu s$
	Slew rate ($T_{amb} = +25^{\circ}C$)	8	16		8	16		
	$V_{in} = 10V$, $R_L = 2k\Omega$, $C_L = 100pF$, unity gain							

Table 3. $V_{CC} = \pm 15V$, $T_{amb} = +25^{\circ}C$ (unless otherwise specified) (continued)

Symbol	Parameter	TL084I,M,AC,AI,AM, BC,BI,BM			TL084C			Unit
		Min.	Typ.	Max.	Min.	Typ.	Max.	
t_r	Rise time ($T_{amb} = +25^{\circ}C$) $V_{in} = 20mV$, $R_L = 2k\Omega$, $C_L = 100pF$, unity gain		0.1			0.1		μs
K_{ov}	Overshoot ($T_{amb} = +25^{\circ}C$) $V_{in} = 20mV$, $R_L = 2k\Omega$, $C_L = 100pF$, unity gain		10			10		%
GBP	Gain bandwidth product ($T_{amb} = +25^{\circ}C$) $V_{in} = 10mV$, $R_L = 2k\Omega$, $C_L = 100pF$, $f = 100kHz$	2.5	4		2.5	4		MHz
R_i	Input resistance		10^{12}			10^{12}		Ω
THD	Total harmonic distortion ($T_{amb} = +25^{\circ}C$, $f = 1kHz$, $R_L = 2k\Omega$, $C_L = 100pF$, $A_v = 20dB$, $V_o = 2V_{pp}$)		0.01			0.01		%
e_n	Equivalent input noise voltage $R_S = 100\Omega$, $f = 1KHz$		15			15		$\frac{nV}{\sqrt{Hz}}$
\emptyset_m	Phase margin		45			45		degrees
V_{o1}/V_{o2}	Channel separation $A_v = 100$		120			120		dB

1. The input bias currents are junction leakage currents which approximately double for every $10^{\circ}C$ increase in the junction temperature.

Figure 2. Maximum peak-to-peak output voltage versus frequency

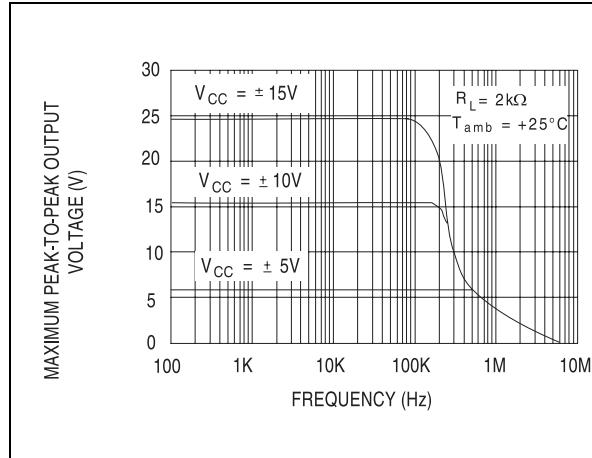


Figure 3. Maximum peak-to-peak output voltage versus frequency

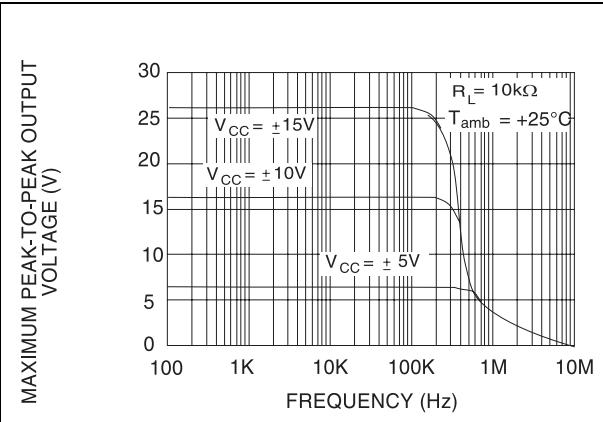


Figure 4. Maximum peak-to-peak output voltage versus frequency

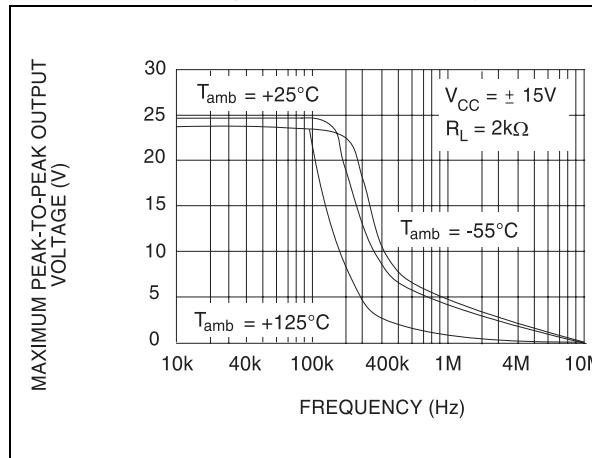


Figure 5. Maximum peak-to-peak output voltage versus free air temperature

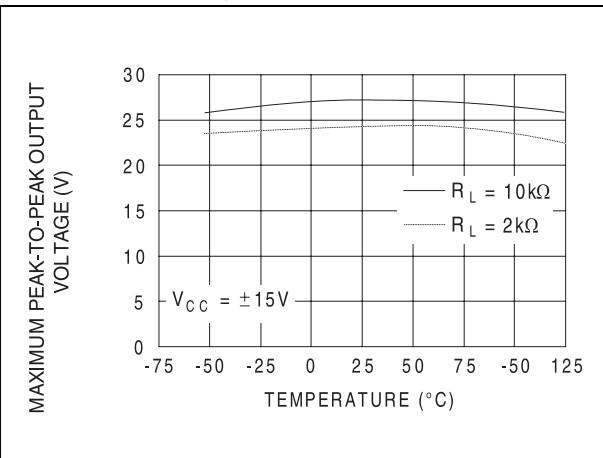


Figure 6. Maximum peak-to-peak output voltage versus load resistance

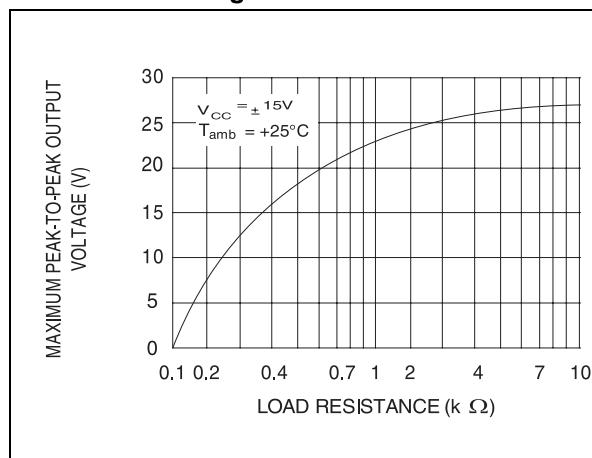


Figure 7. Maximum peak-to-peak output voltage versus supply voltage

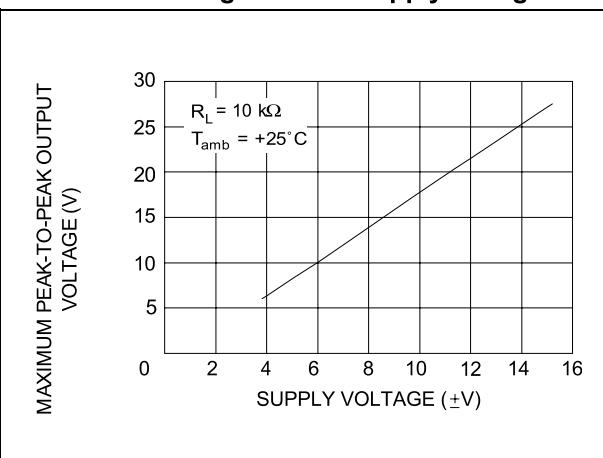


Figure 8. Input bias current versus free air temperature

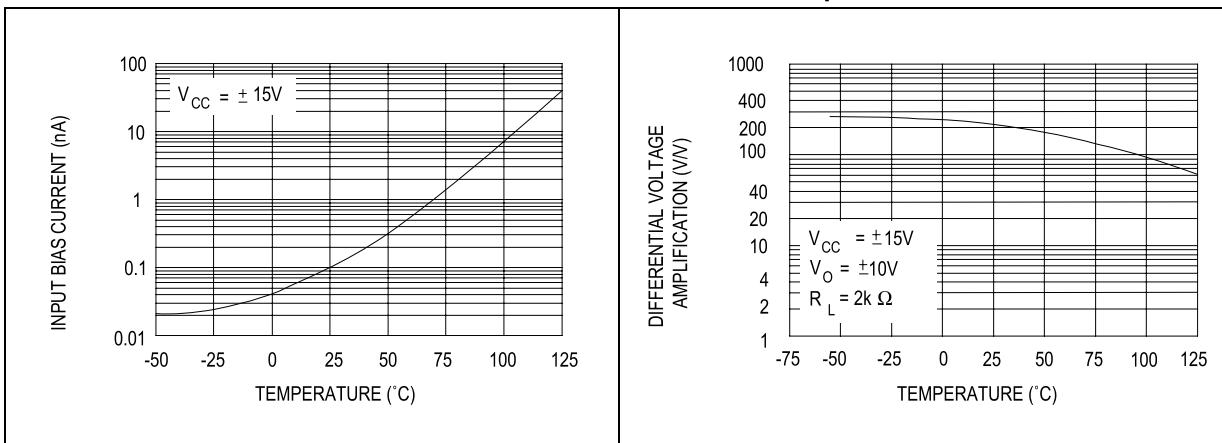


Figure 10. Large signal differential voltage amplification and phase shift versus frequency

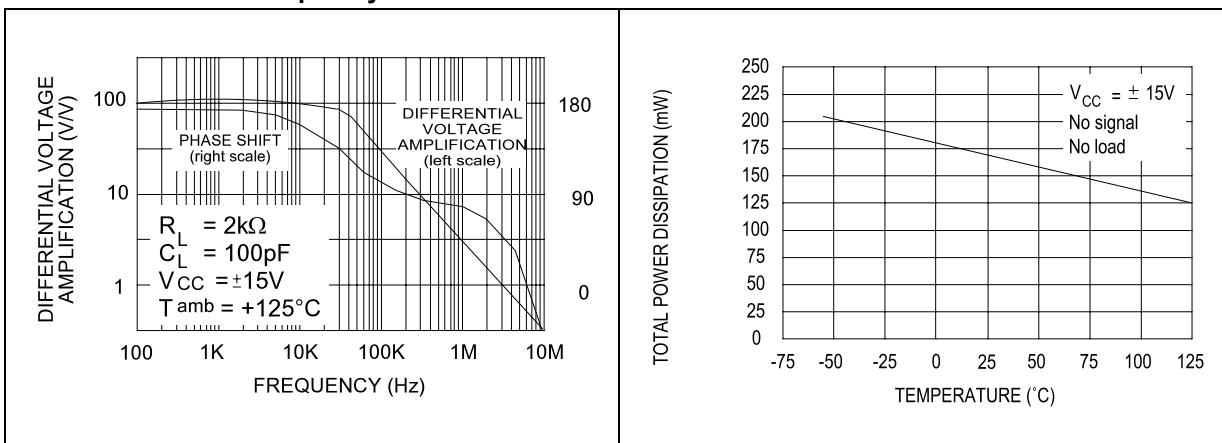


Figure 12. Supply current per amplifier versus free air temperature

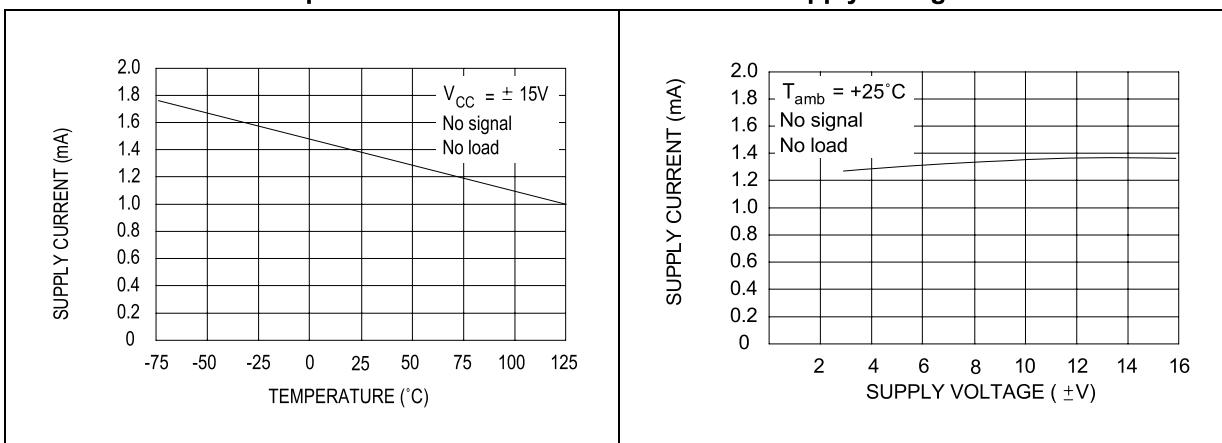


Figure 9. Large signal differential voltage amplification versus free air temperature

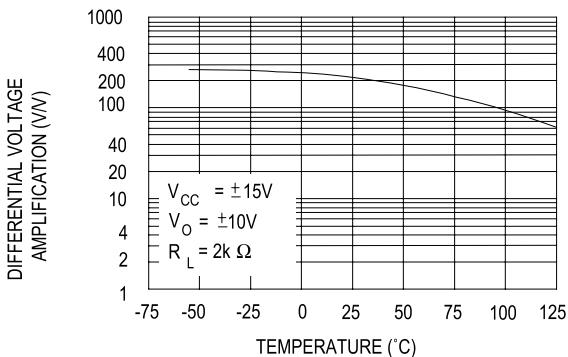


Figure 11. Total power dissipation versus free air temperature

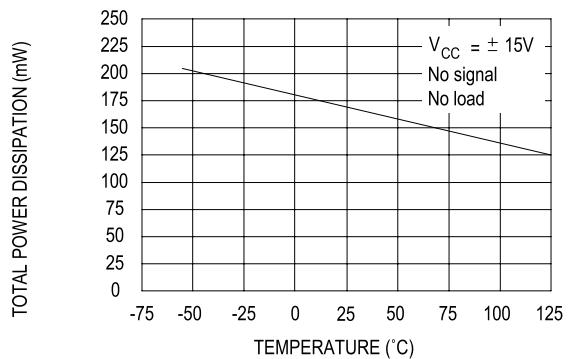


Figure 13. Supply current per amplifier versus supply voltage

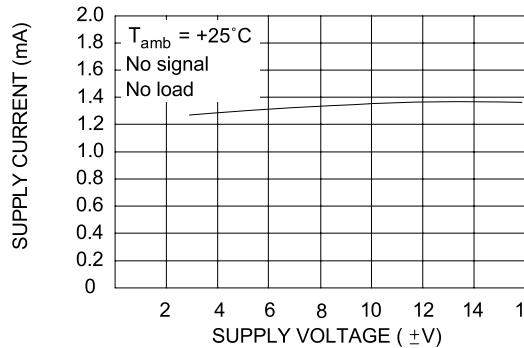


Figure 14. Common mode rejection ratio versus free air temperature

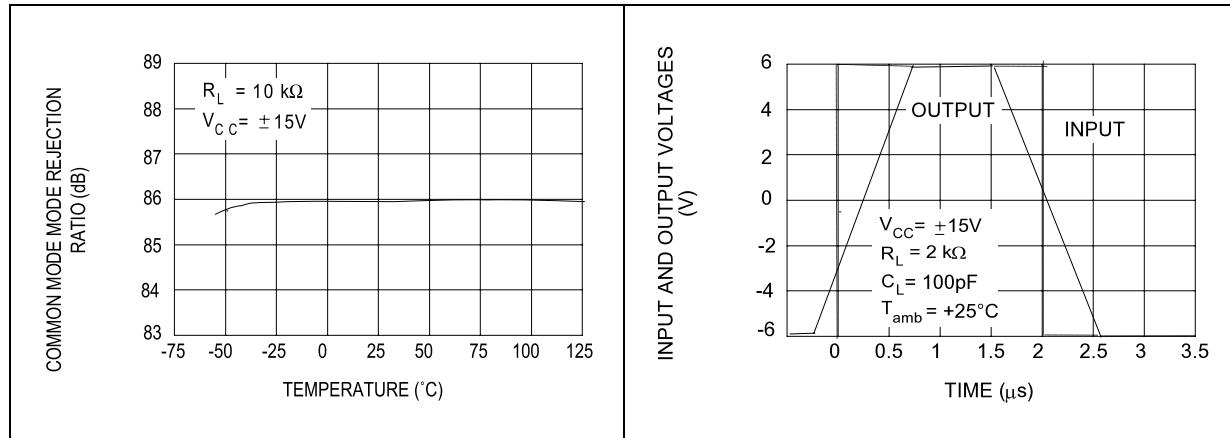


Figure 15. Voltage follower large signal pulse response

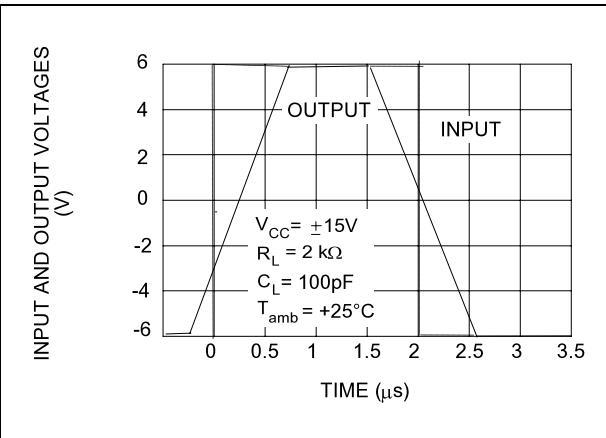


Figure 16. Output voltage versus elapsed time **Figure 17. Equivalent input noise voltage versus frequency**

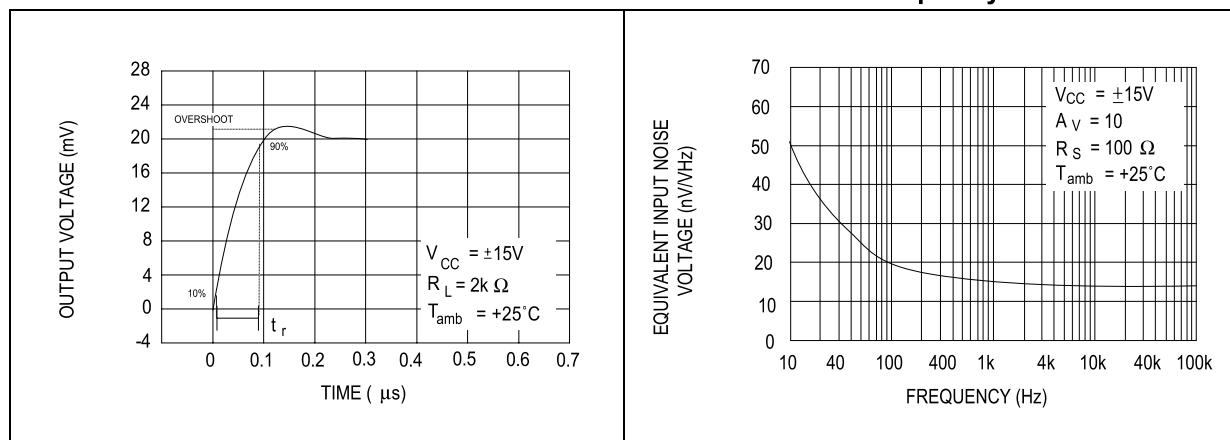
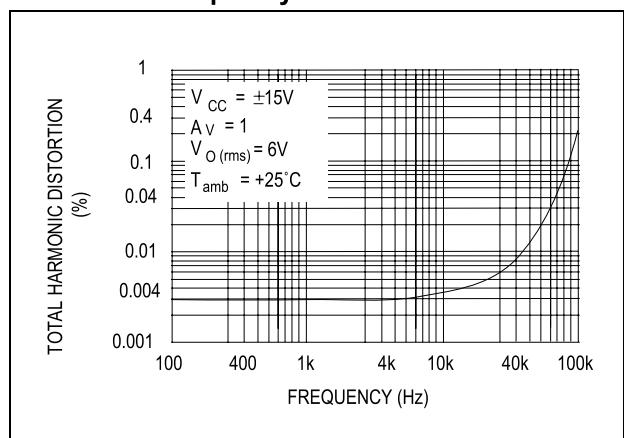


Figure 18. Total harmonic distortion versus frequency



Parameter measurement information

Figure 19. Voltage follower

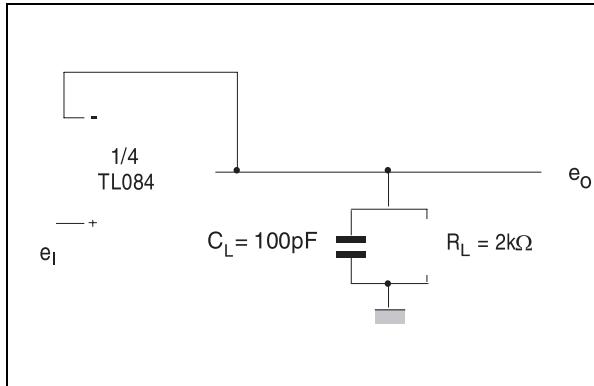
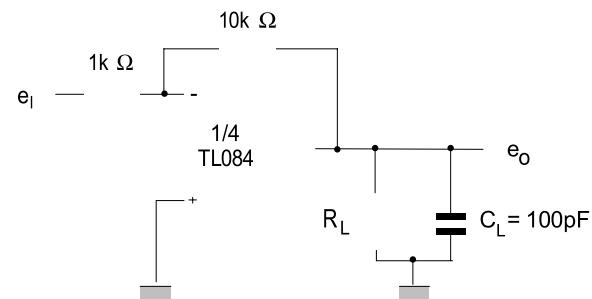


Figure 20. Gain-of-10 inverting amplifier



4 Typical applications

Figure 21. Audio distribution amplifier

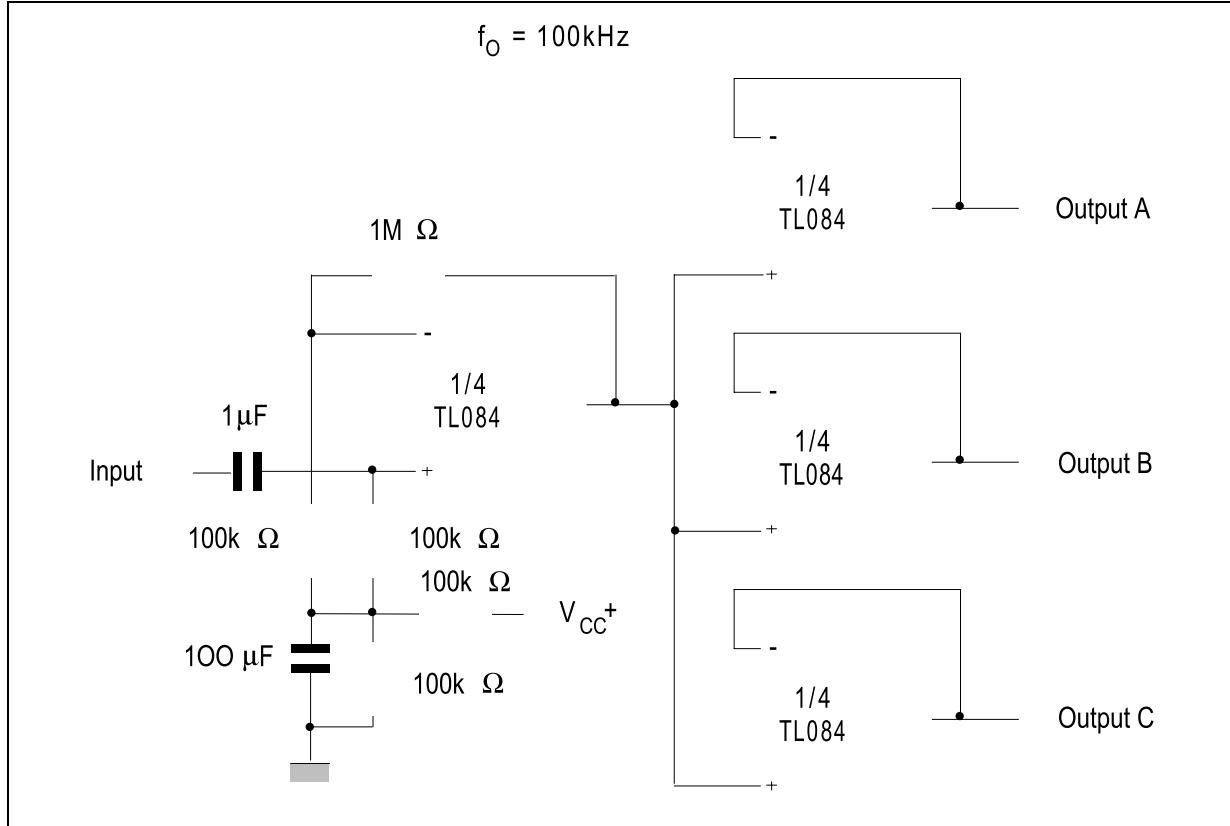
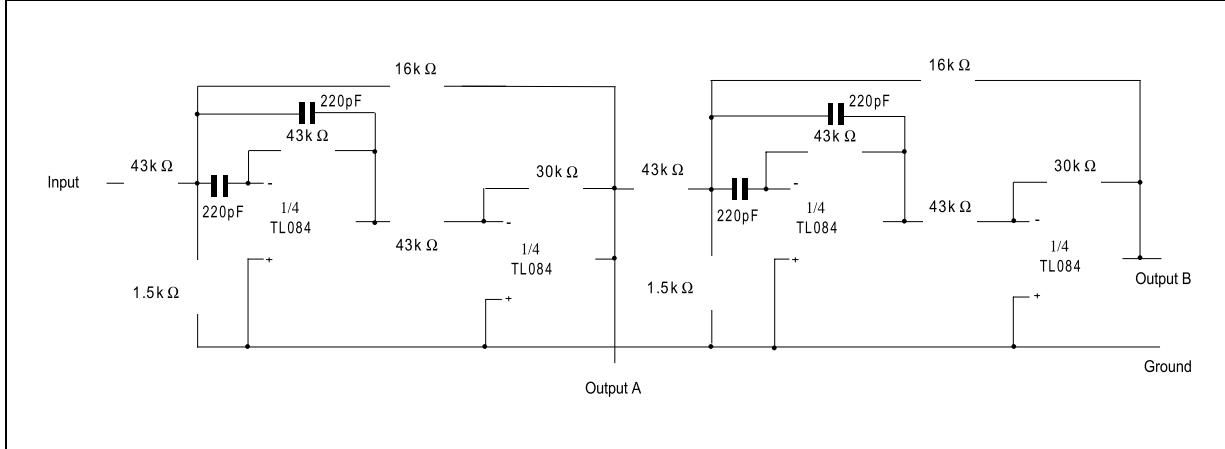
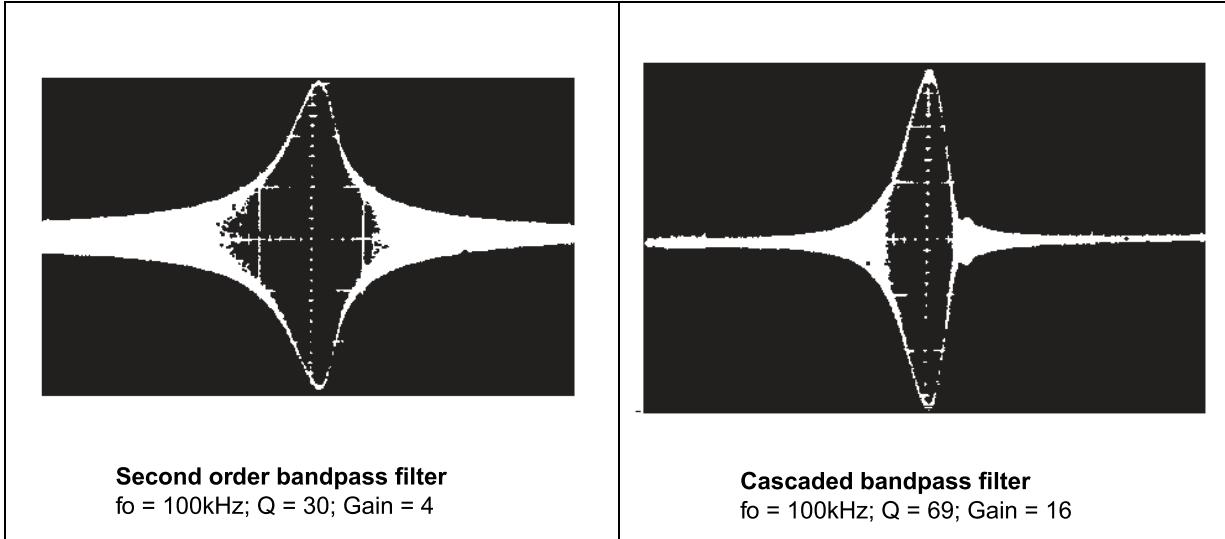
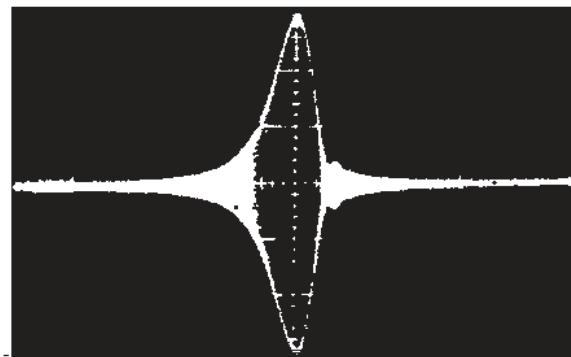


Figure 22. Positive feedback bandpass filter**Figure 23. Output A****Figure 24. Output B**

5 Package information

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com.

Figure 25. TSSOP14 package mechanical data

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A			1.2			0.047
A1	0.05		0.15	0.002	0.004	0.006
A2	0.8	1	1.05	0.031	0.039	0.041
b	0.19		0.30	0.007		0.012
c	0.09		0.20	0.004		0.0089
D	4.9	5	5.1	0.193	0.197	0.201
E	6.2	6.4	6.6	0.244	0.252	0.260
E1	4.3	4.4	4.48	0.169	0.173	0.176
e		0.65 BSC			0.0256 BSC	
K	0°		8°	0°		8°
L	0.45	0.60	0.75	0.018	0.024	0.030

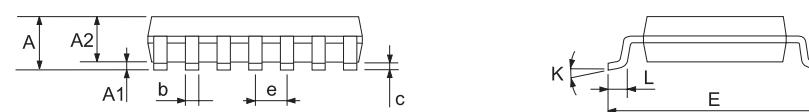
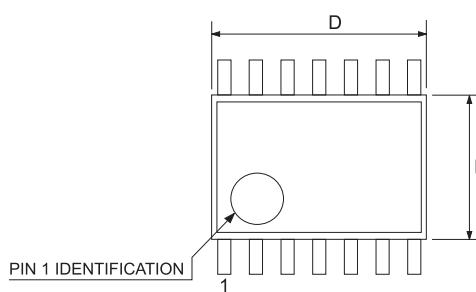



Figure 26. DIP14 package mechanical data

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
a1	0.51			0.020		
B	1.39		1.65	0.055		0.065
b		0.5			0.020	
b1		0.25			0.010	
D			20			0.787
E		8.5			0.335	
e		2.54			0.100	
e3		15.24			0.600	
F			7.1			0.280
I			5.1			0.201
L		3.3			0.130	
Z	1.27		2.54	0.050		0.100

The figure contains three technical drawings of a DIP14 package. The top drawing shows a side view with dimensions: height Z, width b, pitch e3, lead thickness B, lead height e, and lead width z. The middle drawing shows a top-down view of the package body with pins numbered 1 through 14 in a row, and pins 7 and 8 highlighted. The bottom drawing shows a side view of the package with lead length L and lead thickness F.

Figure 27. SO-14 package mechanical data

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A			1.75			0.068
a1	0.1		0.2	0.003		0.007
a2			1.65			0.064
b	0.35		0.46	0.013		0.018
b1	0.19		0.25	0.007		0.010
C		0.5			0.019	
c1	45° (typ.)					
D	8.55		8.75	0.336		0.344
E	5.8		6.2	0.228		0.244
e		1.27			0.050	
e3		7.62			0.300	
F	3.8		4.0	0.149		0.157
G	4.6		5.3	0.181		0.208
L	0.5		1.27	0.019		0.050
M			0.68			0.026
S	8° (max.)					

The figure contains three detailed mechanical drawings of the SO-14 package:

- Top View:** Shows the rectangular package body with lead positions labeled 1 through 14. Lead 1 is at the bottom left, and lead 14 is at the top left. Lead 8 is at the top right, and lead 7 is at the bottom right. Other leads are numbered sequentially from left to right along the top and bottom edges.
- Side Cross-Section:** Provides a vertical view of the package thickness and internal structure. Labels include: **L** (total length), **G** (lead pitch), **C** (lead height), **c1** (lead angle), **a1** (lead gap), **E** (lead width), **b1** (lead thickness), and **s** (lead stop). The cross-section shows the lead frame, chip, and encapsulation.
- Bottom Lead Profile:** A detailed view of the lead frame showing the lead angle (c1) and lead thickness (b1).

6 Ordering information

Table 4. Order codes

Part number	Temperature range	Package	Packing	Marking
TL084MN TL084AMN TL084BMN	-55°C, +125°C	DIP14	Tube	TL084MN TL084AMN TL084BMN
TL084MD/MDT TL084AMD/AMDT TL084BMD/BMDT		SO-14	Tube or tape & reel	084M 084AM 084BM
TL084MP/MPT TL084AMP/AMPT TL084BMP/BMPT		TSSOP14	Tube or tape & reel	084M 084AM 084BM
TL084IN TL084AIN TL084BIN	-40°C, +105°C	DIP14	Tube	TL084IN TL084AIN TL084BIN
TL084ID>IDT TL084AID/AIDT TL084BID/BIDT		SO-14	Tube or tape & reel	084I 084AI 084BI
TL084IP/IPT TL084AIP/AIPT TL084BIP/BIPT		TSSOP14	Tube or tape & reel	084I 084AI 084BI
TL084CN TL084ACN TL084BCN	0°C, +70°C	DIP14	Tube	TL084CN TL084ACN TL084BCN
TL084CD/CDT TL084ACD/ACDT TL084BCD/BCDT		SO-14	Tube or tape & reel	084C 084AC 084BC
TL084CP/CPT TL084ACP/ACPT TL084BCP/BCPT		TSSOP14	Tube or tape & reel	084C 084AC 084BC

7 Revision history

Table 5. Document revision history

Date	Revision	Changes
28-Mar-2001	1	Initial release.
30-Jul-2007	2	Added values for R_{thja} , R_{thjc} and ESD in <i>Table 1: Absolute maximum ratings</i> . Added <i>Table 2: Operating conditions</i> . Expanded <i>Table 4: Order codes</i> . Template update.

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